

THERMAL INTERFACE STRUCTURE WITH INTEGRATED LIQUID COOLING AND METHODS

Abstract

5 A method and device for thermal conduction is provided. A thermal
interface device and method of formation is described that includes advantages such
as improved interfacial strength, and improved interfacial contact. Embodiments of
thermal conduction structures are shown that provide composite thermal conduction
and circulated liquid cooling. Embodiments are further shown that require simple,
10 low numbers of manufacturing steps and reduced thermal interface thickness.

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